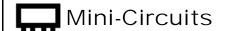


ENV59



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

| Specification | Test/Inspection Condition | Reference/Spec |
|--------------------------------|--|---------------------------------------|
| Operating Temperature | -40° to 85°C | Individual Model Data Sheet |
| Storage Temperature | -65° to 150° C Ambient Environment | Individual Model Data Sheet |
| HTOL | 1000 hours at 85°C | MIL-STD-883, Method 1005, Condition B |
| Temperature Cycling | -65° to 150°C, 500 cycles | JESD22-A104, condition C |
| Autoclave | 121°C, 100% RH, 15 PSIG, 96 hours | JESD22-A102, Condition C |
| High Temp Storage | 150°C 168 hours | JESD22-A103, condition B |
| Solderability, SMT Method | Steam Aging: 8 hours. Solder Reflow for SnAgCu: 245°C+5°C, SnPb: 225°C+5°C | JESD22-B102, Method 2 |
| Marking Resistance to Solvents | Solution A, B, C. Continue with reflow at Tmax: 260°C | JESD22-B017D |
| Solderability, SMT Method | Steam Aging: 8 hours. Solder Reflow for SnAgCu: 245°C+5°C, SnPb: 225°C+5°C | JESD22-B102, Method 2 |

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